

215379US3



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :  
Yoshiaki UEMATSU, et al. : GROUP: 2827  
SERIAL NO: 09/986,282 : EXAMINER: PATEL, I.  
FILED: November 8, 2001 :

**RCE FILED: Herewith**

FOR: A WIRING BOARD AND A METHOD :  
FOR MANUFACTURING THE  
WIRING BOARD

**AMENDMENT**

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Pursuant to the Request for Continued Examination filed herewith, and in response to the Office Action dated January 2, 2003, and the Advisory Action dated May 27, 2003, please consider the remarks below and amend the above-identified patent application as follows:

**IN THE CLAIMS**

Please amend Claims 1, 4, 5, 7-9, and 14-20 as shown in marked-up form in the attachment. Claims 1, 4, 5, 7-9, and 14-20 in clean form are shown below:

1. (Amended) A multi-layer wiring board comprising:

a base board including two conductor layers, two insulating layers disposed between the two conductor layers, and at least one of a power layer and a ground layer disposed between the two insulating layers;